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(54) Title: ENCAPSULATING LED LENS WITH BOTTOM REFLECTORS

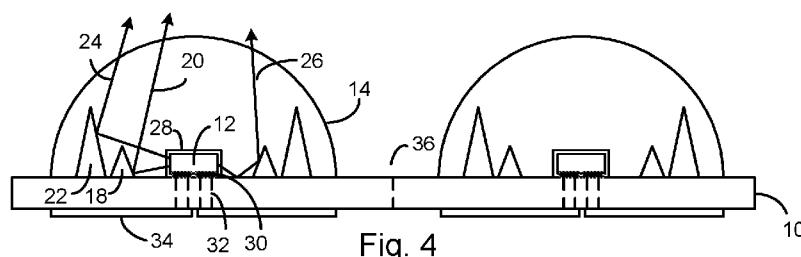


Fig. 4

(57) Abstract: A lens is affixed over an LED die mounted on a substrate to encapsulate the LED die. The lens may have a top surface shaped as a dome or other shape to achieve the desired light pattern. The lens has a cavity for the LED die. A reflector pattern is molded into the bottom surface of the lens, such as one or more facet rings with an angled surface surrounding the LED die. The angled surface of the facet ring reflects the downward or shallow light emission from the LED die upward. A plurality of facet rings of different radii and heights may be formed in the bottom of the lens for shaping the light emission. Any suitable shape of facet may be used. The facet rings may be formed to cause the LED module to emit a narrow beam or other light emission patterns.



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ENCAPSULATING LED LENS WITH BOTTOM REFLECTORS

FIELD OF THE INVENTION

This invention relates to encapsulating light emitting diodes (LEDs) and, in particular, to encapsulating an LED die with a lens having bottom reflective features.

5 BACKGROUND

It is common to mount an LED die on a submount (a substrate) and position a pre-formed dome lens over the LED die to encapsulate it. The dome lens has a cavity for the LED die that contains a transparent or translucent resilient silicone. The bottom of the lens is otherwise flat. When the dome lens is pressed over the LED die, the silicone fills the voids
10 around the LED die.

With such a structure, the light emission is generally lambertian. Light emitted from the sides of the LED die or at a shallow angle is frequently wasted light since the useful light emission is generally the light emitted in a forward direction. Such encapsulated LED dies have been mounted in small reflective conical cups to direct all the light in the forward
15 direction, but such cups add cost and size to the LED module.

Additionally, light emitted in a downward direction may be absorbed somewhat by the submount surface and reflected at a shallow angle. Therefore, this light may also be wasted.

What is needed is a lens encapsulation technique that does not suffer from the
20 drawbacks mentioned above.

SUMMARY

In one embodiment, an array of LED dies is mounted on a submount wafer, where electrodes of the LED dies are electrically connected to metal pads on the submount wafer. Flip chip LEDs or wire-bonded LEDs may be used. The invention also applies to processing
5 a single LED at a time.

Lenses are pre-formed, such as by a molding process. The lenses may be formed of a hardened silicone or other suitable transparent material. The lenses are typically circular and may have a top surface shaped as a dome or other shape to achieve the desired light pattern. The lenses have a cavity for the LED die. A reflector pattern is molded into the bottom
10 surface of the lens, such as a facet ring with an angled surface. In one embodiment, the facets are angled indentations molded into the bottom surface of the lens. The angles may be flat or rounded.

The bottom of the lens and the facets may be optionally coated with a reflective film, such as a reflective metal film.

15 Softened silicone is dispensed in the cavity.

When the lens is pressed over the LED die, the silicone in the cavity encapsulates the LED die, and the LED die is surrounded by the facet ring. The angled surface of the facet ring reflects the downward or shallow light emission from the LED die upward. If a reflective film does not coat the facets, the upward reflection may be by total internal
20 reflection (TIR).

A plurality of concentric facet rings of different radii and heights may be formed in the bottom of the lens for spreading the light emission. The angles of the different facet rings may be different or the same. In another embodiment, the facet rings need not be circular but may be squares, rectangles, elliptical, or other shapes, depending on the emission pattern
25 desired. Similarly, the lens may have any shape.

The facet rings may be formed to cause the LED module to emit a narrow beam or other light emission patterns. The top surface of the lens may be shaped to achieve any light emission pattern.

5 In another embodiment, the bottom surface of the lens is formed to be rounded to reflect the LED light upward.

The top surface of the submount wafer may be coated with a reflective film.

The encapsulation process may be performed on a wafer scale to simplify handling and reduce costs. After the encapsulation process, the submount wafer is singulated to form the individual LED modules.

10 Other embodiments are described.

BRIEF DESCRIPTION OF THE DRAWINGS

Fig. 1 is a top down view of a submount wafer populated with an array of LED dies.

Fig. 2 is a cross-sectional view bisecting a lens, illustrating the LED die cavity and reflective facets formed in the bottom of the lens, in accordance with one embodiment of the
15 invention.

Fig. 3 is a bottom up view of the lens of Fig. 2 showing the apexes of the circular facets and the LED die cavity.

Fig. 4 is a cross-sectional view of a submount wafer populated with LED dies, where the lenses of Fig. 2 have been positioned over the LED dies to encapsulate them.

20 Fig. 5 is a cross-sectional view bisecting a lens in accordance with another embodiment of the invention.

Elements that are the same or similar are labeled with the same numeral.

DETAILED DESCRIPTION

Fig. 1 illustrates a submount wafer 10 populated with an array of LED dies 12. In another embodiment, only a single LED die 12 is processed at a time. The LED dies 12 may be any type, including flip chips, vertical, wire bonded, etc. In the simplified example, only twelve LED dies 12 are shown but, in an actual embodiment, hundreds of LED dies 12 would typically be mounted on a single submount wafer 10. The LED dies 12 are typically about 1 mm per side. The submount wafer 10 may be conventional, such as a ceramic wafer with conductive traces, or may be formed of another material. The wafer 10 may also be rectangular, hexagonal, or any other suitable shape.

Fig. 2 is a cross-sectional view of a pre-formed lens 14, in accordance with one embodiment of the invention. Fig. 3 is a bottom up view of the lens 14 illustrating the apexes of the facets 18 and 22 and the outline of the LED die cavity 16. Fig. 4 illustrates the lenses 14 mounted over the LED dies 12. The lens 14 may be a molded silicone. For a typical LED die, the lens 14 may have a diameter about 3-5 mm.

The lens 14 has a central cavity 16, slightly larger than the LED die 12. Surrounding the cavity 16 are reflective features that redirect the LED die's side light upwards. In the example of Fig. 2, a circular first facet 18 has an angled face that reflects any side light upward, as shown in Fig. 4 by light ray 20. A circular second facet 22 extends a greater distance into the lens 14 and has an angled face that also reflects impinging light upward, such as light ray 24 in Fig. 4. Any other type of reflective feature may be formed in the bottom surface of the lens 14 to reflect the light upwards.

In another embodiment, the light-impinging faces of the facets 18 and 22 are not flat but are curved (such as parabolically) to create a narrower beam. Adding more concentric rings of facets of different heights may serve to spread out the light emission across the top surface of the lens 14.

In another embodiment, the facets 18 and 22 form rings that are squares, rectangles, elliptical, or other shape, depending on the desired emission pattern. The lens 14 may also be square, rectangular, elliptical, or other shape, depending on the desired emission pattern.

In one embodiment, the facets 18 and 22 as well as the rest of the bottom surface of the lens 14 are coated with a reflective film, such as a reflective metal film. In another embodiment, there is no reflective film coating the facets 18 and 22, and the facets 18 and 22 define an air gap. The different indices of refraction at the lens/air interface results in TIR when the light is impinging within a range of angles. Even light passing through the facets 18 and 22 may still be emitted by the light being refracted by the facets 18 and 22 and, in some cases, reflected off the surface of the submount wafer 10.

The submount wafer 10 may have a reflective layer, such as white paint or a reflective metal ring. Fig. 4 illustrates a light ray 26 reflecting off the submount wafer 10 surface.

Rather than forming rings of facets, the facets may be an array of individual facets to more uniformly distribute the light. In such a case, Fig. 2 would illustrate four separate facets, each having a rectangular reflective light-impinging surface.

An adhesive silicone 28 (Fig. 4), with an index of refraction typically between that of the LED die 12 and the lens 14, is dispensed in the cavity 16 and on the bottom surface of the lens 14. The silicone 28 in the cavity 16 is deformable. The lens 14 is then pressed over the LED die 12, as shown in Fig. 4, to cause the silicone 28 in the cavity 16 to deform around the LED die 12 to encapsulate the LED die 12. The encapsulation may be performed in a vacuum to remove air. The adhesive silicone is then cured to harden. In another embodiment, the silicone 28 used in the cavity 16 to encapsulate the LED die 12 is different from the adhesive on the bottom of the lens 14 to enable optimizing both materials. The silicone 28 in the cavity 16 need not be an adhesive and may stay resilient to adapt to differences in the coefficients of thermal expansion of the LED die 12 and the lens 14.

Fig. 4 illustrates the LED die electrodes 30 bonded to corresponding metal pads of the submount wafer 10. The metal pads of the submount wafer 10 are connected to vias 32 extending through the submount wafer 10 and terminating in bottom pads 34. The pads 34 may be soldered to a printed circuit board after singulation. A singulation line 36 is shown. Singulation may be by sawing or other technique. Singulation may divide wafer 10 into individual devices or arrays of devices.

The submount wafer 10 and the singulated submount portion may also be referred to as a substrate. The substrate may employ any type of electrical connector to a power source instead of the pads 34.

Fig. 5 illustrates another shape of the bottom of the lens 42 that acts to reflect the light rays 44 of the LED die 12 upward. The shape is generally a parabolic bowl shape connected to an upper spherical shape. Many other shapes of reflective surfaces may be used to reflect the low angle LED light so that the emitted beam is relatively narrow. Virtually any beam shape is achievable. The reflection may be by TIR or the bottom surface of the lens 42 is coated with a reflective material.

10 The top surface of the lens 14 may be any shape to further shape the light emission pattern. Some shapes include a roughened surface, a dimpled surface, a Fresnel lens surface, a collimating lens surface, etc. A majority of the LED die emission is from its top surface, so the lens top surface shape will be the primary means for directing the light. The combination of the lens shape and reflector shape can be used to create a very narrow beam of bright light.

15 Rather than the lens 14 being pre-formed, the lens 14 may be molded directly over the LED dies 12 in a compression molding process and cured. In such a case no adhesive or cavity filling material is used.

The LED die 12 may include phosphor for creating any light emission color, including white light. Multiple LED dies may be interconnected and arranged in an array for a single LED module and all the LED dies encapsulated by a single lens with a suitably large cavity.

The lens 14 may contain phosphors to convert the light emitted by LED 14 into white light or any other suitable light. Typically LED 12 would emit blue light and lens 14 would include YAG phosphors.

25 By using the present invention, there is no need for mounting the LED die in a reflective cup.

While particular embodiments of the present invention have been shown and described, it will be obvious to those skilled in the art that changes and modifications may be made without departing from this invention in its broader aspects and, therefore, the appended claims are to encompass within their scope all such changes and modifications as

5 fall within the true spirit and scope of this invention.

CLAIMS

What is claimed is:

1. A light emitting device comprising:

a light emitting diode (LED) die mounted on a substrate; and

5 a lens overlying and encapsulating the LED die, the lens having a non-flat bottom surface having at least one angled surface to redirect impinging light upward through a top surface of the lens.
2. The device of Claim 1 wherein the top surface of the lens is a dome.
3. The device of Claim 1 wherein the top surface of the lens is shaped to further
10 redirect light.
4. The device of Claim 1 wherein the bottom surface of the lens contains at least one facet.
5. The device of Claim 4 wherein the at least one facet comprises at least one facet surrounding the LED die.
- 15 6. The device of Claim 4 wherein the at least one facet comprises a light-impinging surface wherein the facet is flat in at least one dimension.
7. The device of Claim 4 wherein the at least one facet comprises a light-impinging surface wherein the facet is curved in at least one dimension.
8. The device of Claim 4 wherein the at least one facet comprises at least a first
20 facet ring surrounding a second facet ring.
9. The device of Claim 4 wherein the at least one facet comprises an array of individual facets.
10. The device of Claim 1 wherein the bottom surface of the lens is curved upward.

11. The device of Claim 1 wherein the lens further comprises a cavity in which the LED die is located, the device further comprising a deformable substance in the cavity to encapsulate the LED die.

12. The device of Claim 1 wherein the substrate has a reflective surface.

5 13. The device of Claim 1 wherein the lens has at least a portion of its bottom surface affixed to the substrate.

14. A method of operating a light emitting device comprising:

energizing a light emitting diode (LED) die, the LED die emitting light from its top surface as well as from its side surfaces; and

10 redirecting at least some of the light emitted by the side surfaces of the LED die by a reflective pattern formed in a bottom surface of a lens encapsulating the LED die.

15 15. The method of Claim 14 wherein the reflective pattern comprises at least one facet, surrounding the LED die, molded into the bottom surface of the lens, the facet having an angled surface that reflects light toward a top surface of the lens.

16. The method of Claim 15 wherein the at least one facet comprises a first facet ring surrounding a second facet ring.

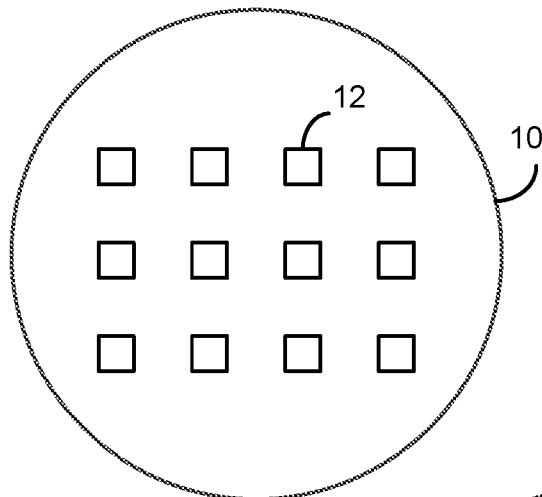


Fig. 1

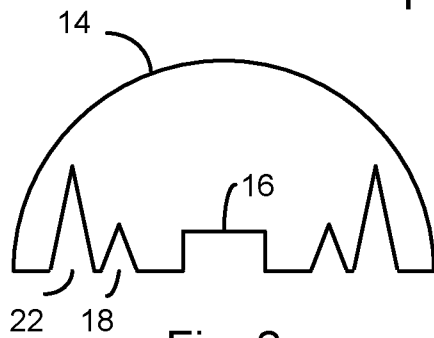


Fig. 2

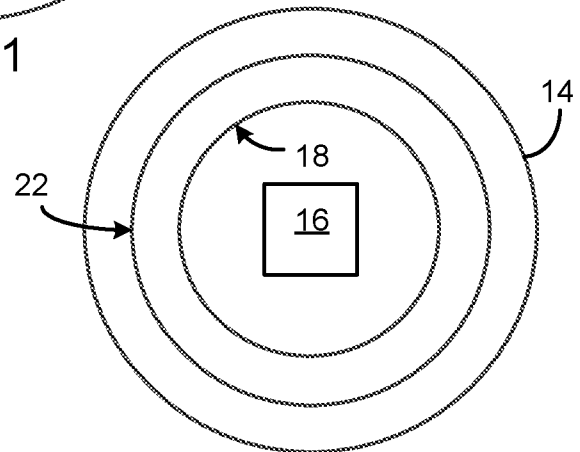


Fig. 3

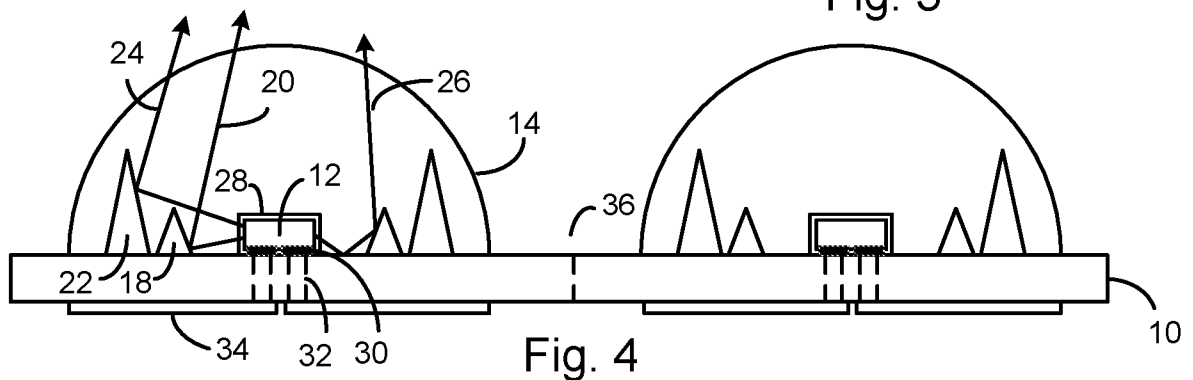


Fig. 4

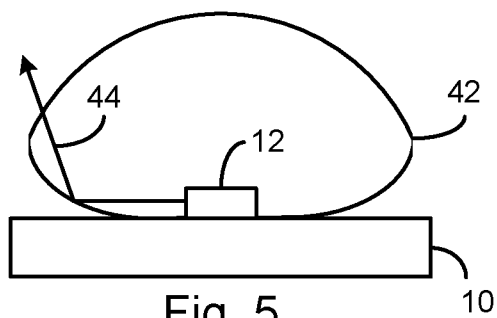


Fig. 5

INTERNATIONAL SEARCH REPORT

International application No
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A. CLASSIFICATION OF SUBJECT MATTER
INV. H01L33/54 H01L33/58 H01L33/60
ADD.

According to International Patent Classification (IPC) or to both national classification and IPC

B. FIELDS SEARCHED

Minimum documentation searched (classification system followed by classification symbols)
H01L

Documentation searched other than minimum documentation to the extent that such documents are included in the fields searched

Electronic data base consulted during the international search (name of data base and, where practicable, search terms used)

EP0-Internal, WPI Data

C. DOCUMENTS CONSIDERED TO BE RELEVANT

Category*	Citation of document, with indication, where appropriate, of the relevant passages	Relevant to claim No.
X	US 2010/006877 A1 (CHEN CHUN-MIN [TW]) 14 January 2010 (2010-01-14) paragraphs [0021] - [0026], [0028], [0029]; figures 3A, 5A -----	1-16
X	US 2005/285133 A1 (HUNG CHEN-PIN [TW]) 29 December 2005 (2005-12-29) figure 4 -----	1,14
X	WO 2007/097664 A1 (ZAKRYTOE AKTSIONERNOE OBSHEST [RU]; SHERBAKOV VALENTIN NIKOLAEVICH [R]) 30 August 2007 (2007-08-30) figure 1 -----	1,14
A	US 2003/156417 A1 (GASQUET JEAN-CLAUDE [FR] ET AL) 21 August 2003 (2003-08-21) figure 8 -----	9



Further documents are listed in the continuation of Box C.



See patent family annex.

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"&" document member of the same patent family

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INTERNATIONAL SEARCH REPORT

Information on patent family members

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